

Applications

- LTE handset, data card & mobile router applications

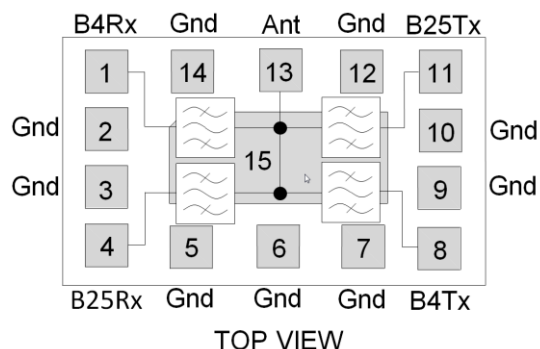


15 Pin 3.6 x 2.0 mm leadless package

Product Features

- BAW and SAW technology
- High cross isolation
- Single-ended (SE) 50 Ohm Rx & Tx ports
- Performance -30 to +90 °C
- Low insertion loss
- RoHS compliant, Pb-free

Functional Block Diagram



General Description

The TQQ2504 is a high-performance Bulk Acoustic Wave (BAW) and Surface Acoustic Wave (SAW) quadplexer bank module designed to meet the strict LTE requirements suitable for carrier aggregation applications. Band 25 uses BAW technology and Band 4 uses SAW technology within one module.

TQQ2504 is specifically designed to meet the high performance expectations of insertion loss, cross isolation and linearity for LTE systems applications under all operating conditions.

The TQQ2504 uses common module packaging techniques to achieve the industry standard 3.6 x 2.0 x 0.9 mm footprint. The quadplexer band module exhibits excellent power handling capabilities.

Pin Configuration – Single Ended

Pin No.	Label
1	Band 4 Rx
4	Band 25 Rx
8	Band 4 Tx
11	Band 25 Tx
13	Antenna
2,3,5,6,7,9,10,12,14,15	GND

Ordering Information

Part No.	Description
TQQ2504	Product description
TQQ2504-EVB	Evaluation board description